

<b>FORM PTO-1449</b>  <b>LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT</b>  (Use several sheets if necessary)	<b>ATTY. DOCKET NO.</b> <b>10020701-1</b>	<b>SERIAL NO.</b>
	<b>APPLICANT</b> <b>Lewis R. D ve, et al.</b>	
	<b>FILING DATE</b> <b>01-20-2004</b>	<b>GROUP</b>

**REFERENCE DESIGNATION U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	*	DOCUMENT NUMBER	DATE	NAME
<i>PR</i>		6,255,730	07-03-2001	Dove et al.
<i>PR</i>		6,457,979	10-01-2002	Dove et al.

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	NAME	TRANSLATION	
					YES	NO

**OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)**

<i>PR</i>	John F. Casey, et al., "Methods for Depositing a Thickfilm Dielectric on a Substrate", Filed June 19, 2003, Pending U.S. Patent Application Serial No. 10/600,600, 14 pages of specification, and five (5) sheets of formal drawings.
<i>PR</i>	John F. Casey, et al., "Methods for Making Microwave Circuits", Filed June 19, 2003, pending U.S. Patent Application Serial No. 10/600,143, 21 pages of specification, and nine (9) sheets of formal drawings.
<i>PR</i>	John F. Casey, et al., "Methods for Forming a Conductor on a Dielectric", Filed June 19, 2003, pending U.S. Patent Application Serial No. 10/601,042, 12 pages of specification, and two (2) sheets of formal drawings.

<b>EXAMINER</b>  <b>BENNY T. LEE</b> PRIMARY EXAMINER	<b>DATE CONSIDERED</b> 18 March 2005
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\* Copies of these references are not enclosed pursuant to 37 CFR 1.98(d). (See accompanying IDS)